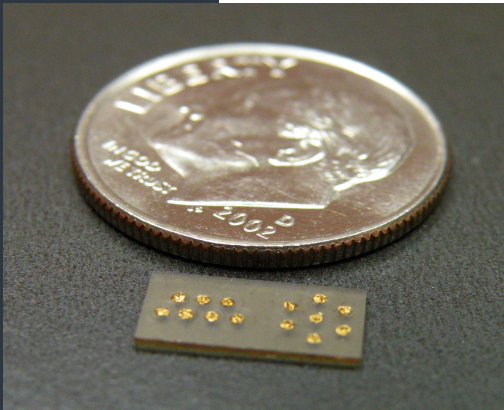


## **THINNERPOSER®** BOARD TO BOARD CONNECTOR



### Ultra Low Profile Interposer

Custom Interconnects introduces the thinnest compliant board to board interposer ever developed: the Thinnerposer® product line. For the ultimate in high density PCB stacking, signal integrity and reliability, the Thinnerposer® meets the challenges of today's designs and will help shape those of the future.

Thinnerposers® incorporate our Fuzz Button® technology into a custom designed low profile connector solution. As such, Custom Interconnects matches your design requirements rather of making you match ours. And because of this approach, our products can be more cost-effective than COTS (Commercial-Off-The-Shelf) connectors.

Thinnerposers® exploit the full potential of Fuzz Buttons®: low signal distortion, robustness and consistency. Couple that with the experience, expertise and dedication of the Custom Interconnects design team — and you have a winning combination that ensures your project's success!

### Custom Interconnects

For over twenty years, the exclusive supplier of high performance Fuzz Button® interconnect solutions to military and commercial customers worldwide.

For more product information, please visit our website:  
[www.custominterconnects.com](http://www.custominterconnects.com)

Custom Interconnects  
2055 S. Raritan St., Unit A  
Denver, CO 80223

[sales@custominterconnects.com](mailto:sales@custominterconnects.com)  
Phone: (303) 934-6600  
Fax: (303) 934-6606

### Product Features

- Low profile to .014 inches
- High GHz Frequencies
- 5+ Amps per Fuzz Button® contact
- High shock and vibration resistance
- For pitches of 1mm and higher
- Contact arrays up to 200 positions
- Extreme environment capable
- Superior impedance matching
- Fully customizable size/shape/contacts

#### Markets

Aerospace  
Military  
Medical  
Communications  
Semiconductor  
Telemetry

#### Applications

Satellites  
UAV / UAS  
Weapon Systems  
Deep Space Probes  
Antenna  
Radar Array  
Test Fixtures  
Grounding  
Heat Dissipation

